

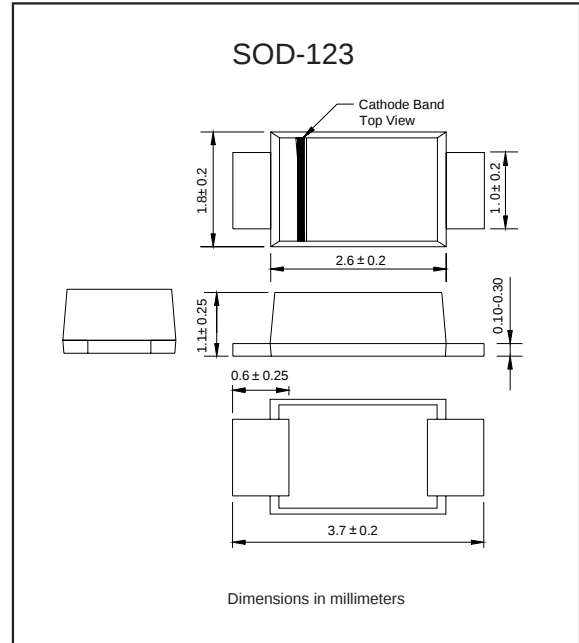
Features

- ◆ Glass passivated device
- ◆ Ideal for surface mounted applications
- ◆ Low reverse leakage
- ◆ Metallurgically bonded construction
- ◆ High temperature soldering guaranteed:
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Compliant to Halogen-free
- ◆ Suffix "-Q1" for AEC-Q101

Mechanical data

- ◆ **Case**: JEDEC SOD-123 molded plastic body over passivated chip
- ◆ **Terminals**: Plated axial leads, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity**: Color band denotes cathode end
- ◆ **Mounting Position**: Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I_O			2.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			50	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^\circ\text{C}$	I_R			5.0	μA
	$V_R = V_{RRM} \quad T_A = 100^\circ\text{C}$				50	
Thermal resistance	Junction to ambient NOTE 1	$R_{\theta JA}$		75		$^\circ\text{C/W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		20		pF
Storage temperature		T_{STG}	-55		+150	$^\circ\text{C}$

SYMBOLS	V _{RRM} ^{*1} (V)	V _{RMS} ^{*2} (V)	V _R ^{*3} (V)	V _F ^{*4} (V)	t _{rr} ^{*5} (ns)	Operating temperature T _J , (°C)
DHE2A-Q1	50	35	50	1.00	50	-55 to +150
DHE2B-Q1	100	70	100			
DHE2D-Q1	200	140	200			
DHE2G-Q1	400	280	400	1.40	75	
DHE2J-Q1	600	420	600			
DHE2K-Q1	800	560	800			
DHE2M-Q1	1000	700	1000			

- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum forward voltage@ $I_F=1.0\text{A}$
- *5 Maximum Reverse recovery time, note 2

Note: 1.P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas
 2. Reverse recovery time test condition, $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$

Rating and characteristic curves

FIG. 1- FORWARD CURRENT DERATING CURVE

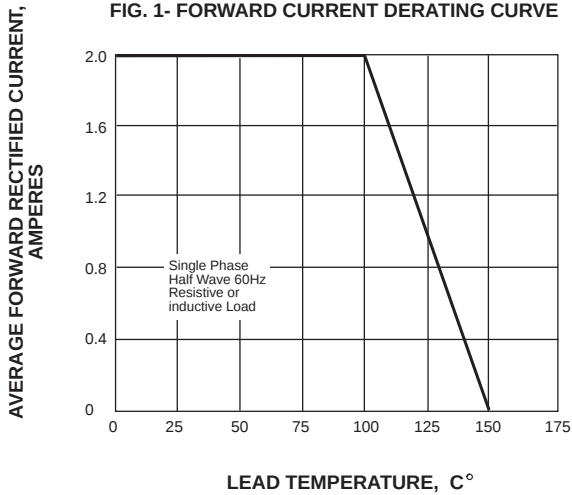


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

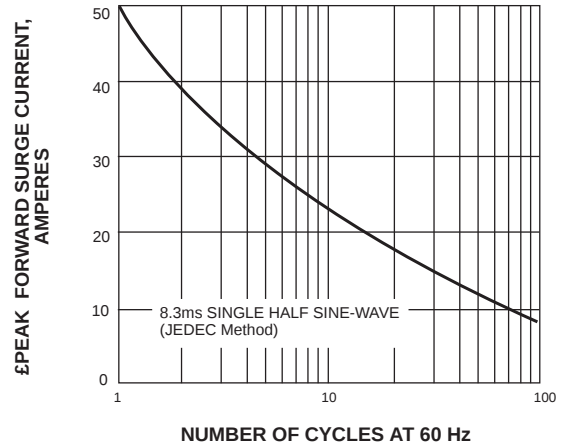


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

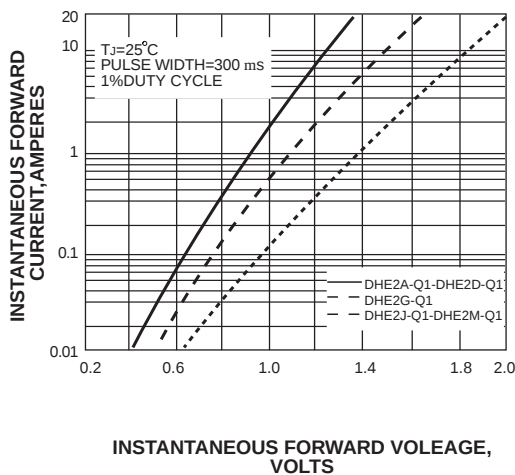


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

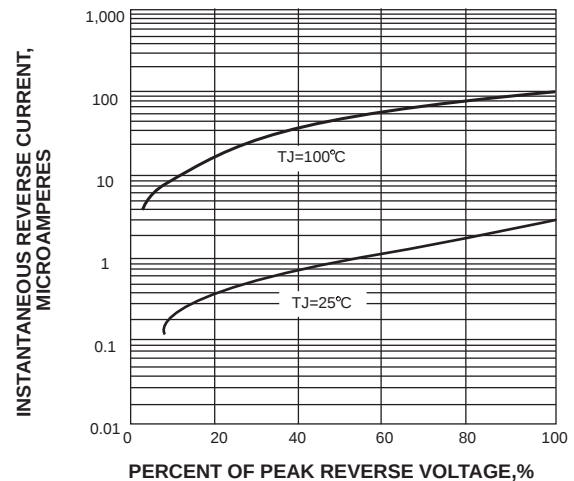


FIG. 5-TYPICAL JUNCTION CAPACITANCE

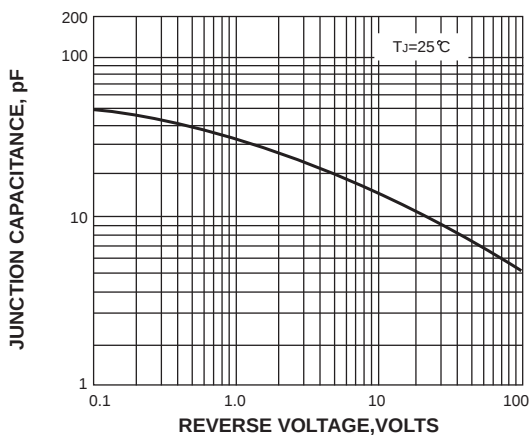
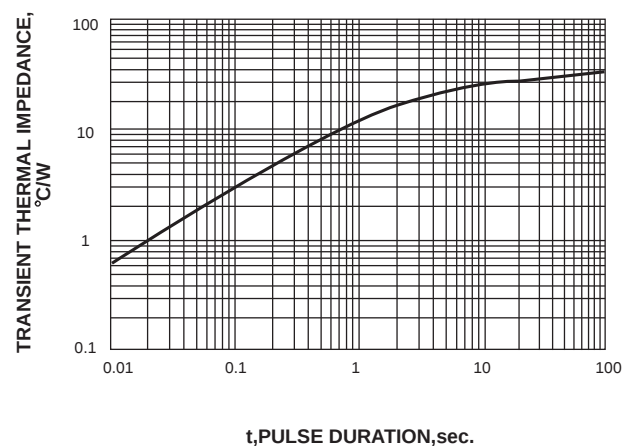


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



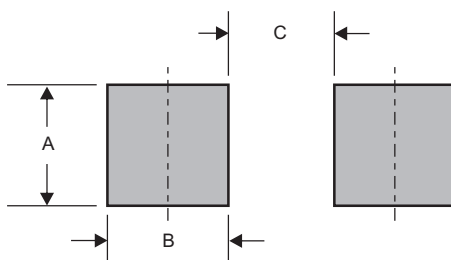
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
DHE2A-Q1	U2A
DHE2B-Q1	U2B
DHE2D-Q1	U2D
DHE2G-Q1	U2G
DHE2J-Q1	U2J
DHE2K-Q1	U2K
DHE2M-Q1	U2M

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123	0.075 (1.90)	0.055 (1.40)	0.075 (1.90)